

# CD74AC151 8-Line to 1-Line Data Selector/Multiplexer

## 1 Features

- AC types feature 1.5V to 5.5V operation and balanced noise immunity at 30% of the supply voltage
- 8-line to 1-line multiplexers can perform as:
  - Boolean function generators
  - Parallel-to-serial converters
  - Data source selectors
- Speed of bipolar F, AS, and S, with significantly reduced power consumption balanced propagation delays
- $\pm 24\text{mA}$  output drive current
  - Fanout to 15 F devices
- SCR-latchup-resistant CMOS process and circuit design
- Exceeds 2k V ESD protection per MIL-STD-883, method 3015

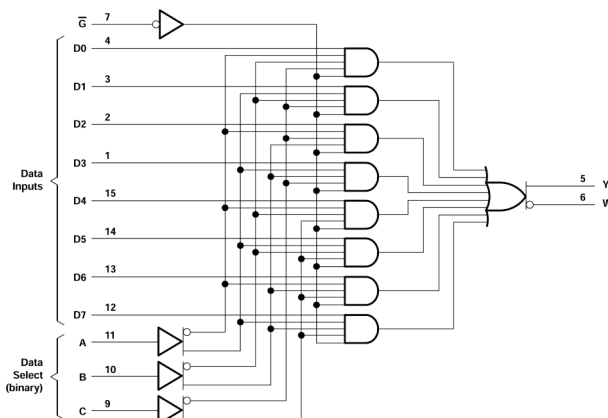
## 2 Description

This data selector/multiplexer provides full binary decoding to select one of eight data sources. The strobe ( $\bar{G}$ ) input must be at a low logic level to enable the inputs. A high level at the strobe terminal forces the W output high and the Y output low.

### Package Information

PART NUMBER	PACKAGE <sup>(1)</sup>	PACKAGE SIZE <sup>(2)</sup>	BODY SIZE <sup>(3)</sup>
CD74AC151	D (SOIC, 16)	9.90mm × 6mm	9.90mm × 3.90mm
	N (PDIP, 16)	19.3mm × 9.4mm	19.3mm × 6.35mm

- (1) For more information, see [Mechanical, Packaging, and Orderable Information](#).
- (2) The package size (length × width) is a nominal value and includes pins, where applicable.
- (3) The body size (length × width) is a nominal value and does not include pins.



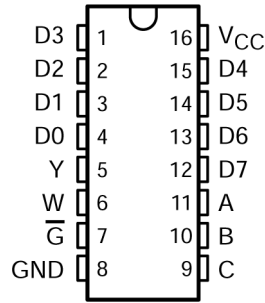
Logic Diagram (Positive Logic)



## Table of Contents

<b>1 Features</b> .....	1	6.1 Functional Block Diagram.....	9
<b>2 Description</b> .....	1	6.2 Device Functional Modes.....	9
<b>3 Pin Configuration and Functions</b> .....	3	<b>7 Application and Implementation</b> .....	10
<b>4 Specifications</b> .....	4	7.1 Power Supply Recommendations.....	10
4.1 Absolute Maximum Ratings.....	4	7.2 Layout.....	10
4.2 ESD Ratings.....	4	<b>8 Device and Documentation Support</b> .....	11
4.3 Recommended Operating Conditions.....	4	8.1 Documentation Support (Analog).....	11
4.4 Thermal Information.....	5	8.2 Receiving Notification of Documentation Updates....	11
4.5 Electrical Characteristics.....	5	8.3 Support Resources.....	11
4.6 Switching Characteristics, $V_{CC} = 1.5V$ .....	5	8.4 Trademarks.....	11
4.7 Switching Characteristics, $V_{CC} = 3.3V \pm 0.3V$ .....	6	8.5 Electrostatic Discharge Caution.....	11
4.8 Switching Characteristics, $V_{CC} = 5V \pm 0.5V$ .....	6	8.6 Glossary.....	11
4.9 Operating Characteristics.....	6	<b>9 Revision History</b> .....	11
<b>5 Parameter Measurement Information</b> .....	7	<b>10 Mechanical, Packaging, and Orderable Information</b> .....	12
<b>6 Detailed Description</b> .....	9		

### 3 Pin Configuration and Functions



**Figure 3-1. D or N Packages; 16-Pin SOIC or PDIP (Top View)**

#### Pin Functions

PIN		I/O <sup>(1)</sup>	DESCRIPTION
NO.	NAME		
1	D3	I	Data input 3
2	D2	I	Data input 2
3	D1	I	Data input 1
4	D0	I	Data input 0
5	Y	O	Data output
6	W	O	Data output, inverted
7	$\overline{G}$	I	Output strobe, active low
8	GND	—	Ground
9	C	I	Address select C
10	B	I	Address select B
11	A	I	Address select A
12	D7	I	Data input 7
13	D6	I	Data input 6
14	D5	I	Data input 5
15	D4	I	Data input 4
16	V <sub>CC</sub>	—	Positive supply

(1) I = input, O = output, P = power, FB = feedback, GND = ground, N/A = not applicable

## 4 Specifications

### 4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	-0.5	6	V
I <sub>IK</sub> <sup>(2)</sup>	Input clamp current	(V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub> )		±20 mA
I <sub>OK</sub> <sup>(2)</sup>	Output clamp current	(V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )		±50 mA
I <sub>O</sub>	Continuous output current	(V <sub>O</sub> = 0 to V <sub>CC</sub> )		±50 mA
	Continuous current through V <sub>CC</sub> or GND			±100 mA
T <sub>stg</sub>	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 4.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per AEC Q100-002 <sup>(1)</sup>	±2000	V

- (1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.

### 4.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		T <sub>A</sub> = 25°C		-55°C to 125°C		-40°C to 85°C		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
V <sub>CC</sub>	Supply voltage	1.5	5.5	1.5	5.5	1.5	5.5	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 1.5 V	1.2	1.2	1.2	1.2		V
		V <sub>CC</sub> = 3 V	2.1	2.1	2.1			
		V <sub>CC</sub> = 5.5 V	3.85	3.85	3.85			
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 1.5 V		0.3	0.3	0.3		V
		V <sub>CC</sub> = 3 V		0.9	0.9	0.9		
		V <sub>CC</sub> = 5.5 V		1.65	1.65	1.65		
V <sub>I</sub>	Input voltage	0	V <sub>CC</sub>	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 4.5 V to 5.5 V		-24	-24		-24	mA
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 4.5 V to 5.5 V		24	24		24	mA
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 1.5 V to 3 V		50	50		50	ns/V
		V <sub>CC</sub> = 3.6 V to 5.5 V		20	20		20	

- (1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## 4.4 Thermal Information

THERMAL METRIC		D (SOIC)	N (PDIP)	UNIT
		16 PINS	16 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance <sup>(1)</sup>	119.9	67	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics](#) application report.

## 4.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		$V_{CC}$	TA = 25°C		-55°C to 125°C		-40°C to 85°C		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
$V_{OH}$	$V_I = V_{IH}$ or $V_{IL}$	$I_{OH} = -50 \mu A$	1.5 V	1.4	1.4	1.4			V	
			3 V	2.9	2.9	2.9				
			4.5 V	4.4	4.4	4.4				
		$I_{OH} = -4 \text{ mA}$	3 V	2.58	2.4	2.48				
			4.5 V	3.94	3.7	3.8				
			5.5 V		3.85					
$I_{OH} = -75 \text{ mA}^{(1)}$	5.5 V			3.85						
$V_{OL}$	$V_I = V_{IH}$ or $V_{IL}$	$I_{OL} = 50 \mu A$	1.5 V		0.1	0.1	0.1	V		
			3 V		0.1	0.1	0.1			
			4.5 V		0.1	0.1	0.1			
		$I_{OL} = 12 \text{ mA}$	3 V		0.36	0.5	0.44			
			4.5 V		0.36	0.5	0.44			
			5.5 V			1.65	-			
$I_{OL} = 75 \text{ mA}^{(1)}$	5.5 V				1.65					
$I_I$	$V_I = V_{CC}$ or GND		5.5 V	$\pm 0.1$	$\pm 1$	$\pm 1$	$\mu A$			
$I_{CC}$	$V_I = V_{CC}$ or GND, $I_O = 0$		5.5 V	8	160	80	$\mu A$			
$C_i$				10	10	10	pF			

(1) Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

## 4.6 Switching Characteristics, $V_{CC} = 1.5V$

over recommended operating free-air temperature range,  $V_{CC} = 1.5V$ ,  $C_L = 50pF$  (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	-55°C to 125°C		-40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	
$t_{PLH}$	D	Y		169		152	ns
$t_{PHL}$				169		152	
$t_{PLH}$	D	W		186		169	ns
$t_{PHL}$				186		169	
$t_{PLH}$	A, B, or C	Y		228		207	ns
$t_{PHL}$				228		207	
$t_{PLH}$	A, B, or C	W		245		223	ns
$t_{PHL}$				245		223	
$t_{PLH}$	$\bar{G}$	Y		153		139	ns
$t_{PHL}$				153		139	

**CD74AC151**

SCHS333A – MARCH 2003 – REVISED JULY 2024

 over recommended operating free-air temperature range,  $V_{CC} = 1.5V$ ,  $C_L = 50pF$  (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	-55°C to 125°C		-40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	
$t_{PLH}$	$\bar{G}$	W					ns
$t_{PHL}$			169		153		

**4.7 Switching Characteristics,  $V_{CC} = 3.3V \pm 0.3V$** 

 over recommended operating free-air temperature range,  $V_{CC} = 3.3V \pm 0.3V$ ,  $C_L = 50pF$  (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	-55°C to 125°C		-40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	
$t_{PLH}$	D	Y	4.7	18.9	4.9	17.1	ns
$t_{PHL}$			4.7	18.9	4.9	17.1	
$t_{PLH}$	D	W	5.2	20.9	5.4	19	ns
$t_{PHL}$			5.2	20.9	5.4	19	
$t_{PLH}$	A, B, or C	Y	6.4	25.5	6.6	23.2	ns
$t_{PHL}$			6.4	25.5	6.6	23.2	
$t_{PLH}$	A, B, or C	W	6.9	27.4	7.1	24.9	ns
$t_{PHL}$			6.9	27.4	7.1	24.9	
$t_{PLH}$	$\bar{G}$	Y	4.3	17.1	4.4	15.5	ns
$t_{PHL}$			4.3	17.1	4.4	15.5	
$t_{PLH}$	$\bar{G}$	W	4.7	18.9	4.9	17.2	ns
$t_{PHL}$			4.7	18.9	4.9	17.2	

**4.8 Switching Characteristics,  $V_{CC} = 5V \pm 0.5V$** 

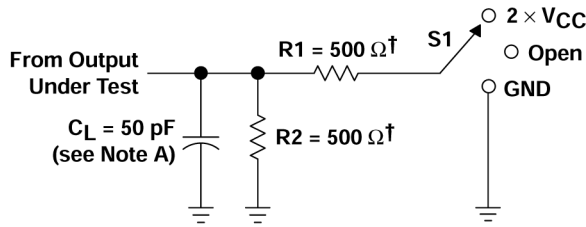
 over recommended operating free-air temperature range,  $V_{CC} = 5V \pm 0.5V$ ,  $C_L = 50pF$  (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	-55°C to 125°C		-40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	
$t_{PLH}$	D	Y	3.4	13.5	3.5	12.3	ns
$t_{PHL}$			3.4	13.5	3.5	12.3	
$t_{PLH}$	D	W	3.7	14.9	3.8	13.5	ns
$t_{PHL}$			3.7	14.9	3.8	13.5	
$t_{PLH}$	A, B, or C	Y	4.6	18.2	4.7	16.5	ns
$t_{PHL}$			4.6	18.2	4.7	16.5	
$t_{PLH}$	A, B, or C	W	4.9	19.6	5.1	17.8	ns
$t_{PHL}$			4.9	19.6	5.1	17.8	
$t_{PLH}$	$\bar{G}$	Y	3.1	12.2	3.1	11.1	ns
$t_{PHL}$			3.1	12.2	3.1	11.1	
$t_{PLH}$	$\bar{G}$	W	3.4	13.5	3.5	12.3	ns
$t_{PHL}$			3.4	13.5	3.5	12.3	

**4.9 Operating Characteristics**
 $V_{CC} = 5V$ ,  $T_A = 25^\circ C$ 

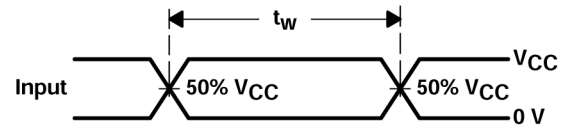
PARAMETER		TYP	UNIT
$C_{pd}$	Power dissipation capacitance	120	pF

## 5 Parameter Measurement Information

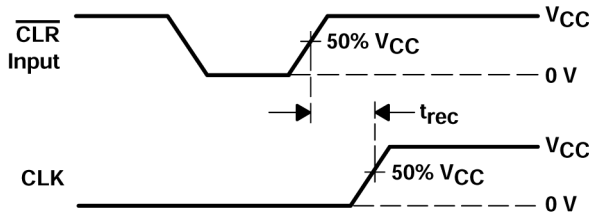


† When  $V_{CC} = 1.5\text{ V}$ ,  $R1 = R2 = 1\text{ k}\Omega$

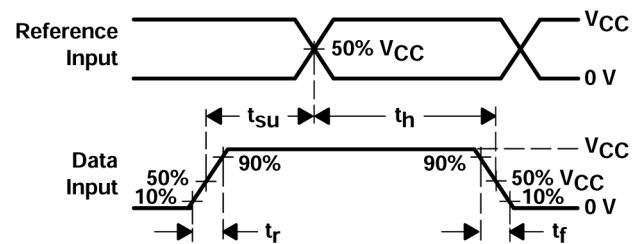
LOAD CIRCUIT



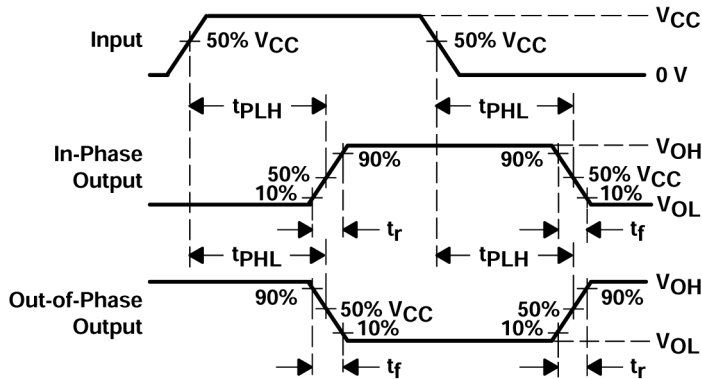
VOLTAGE WAVEFORMS  
PULSE DURATION



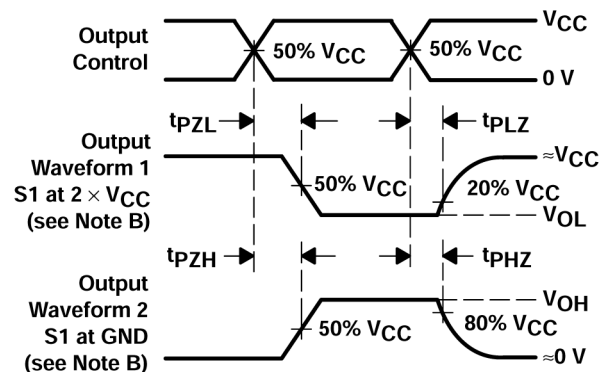
VOLTAGE WAVEFORMS  
RECOVERY TIME



VOLTAGE WAVEFORMS  
SETUP AND HOLD AND INPUT RISE AND FALL TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES



VOLTAGE WAVEFORMS  
OUTPUT ENABLE AND DISABLE TIMES

- $C_L$  includes probe and test-fixture capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r = 3\text{ ns}$ ,  $t_f = 3\text{ ns}$ . Phase relationships between waveforms are arbitrary.
- For clock inputs,  $f_{max}$  is measured with the input duty cycle at 50%.
- The outputs are measured one at a time with one input transition per measurement.
- $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- $t_{pZL}$  and  $t_{pZH}$  are the same as  $t_{en}$ .
- $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- All parameters and waveforms are not applicable to all devices.

Figure 5-1. Load Circuit and Voltage Waveforms

TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{CC}$
$t_{PHZ}/t_{PZH}$	GND



## 6 Detailed Description

### 6.1 Functional Block Diagram

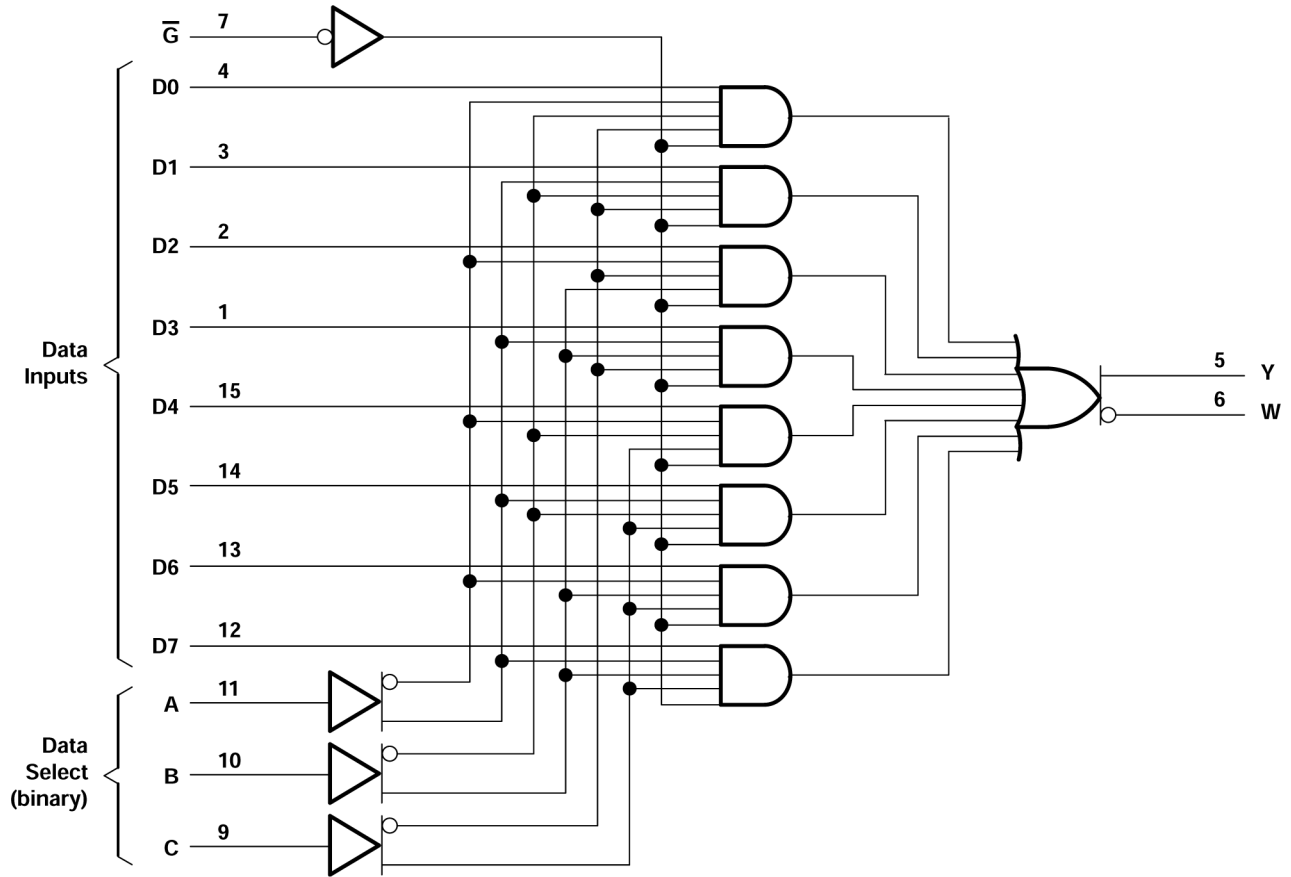


Figure 6-1. Logic Diagram (Positive Logic)

### 6.2 Device Functional Modes

Table 6-1. Function Table

INPUTS			OUTPUTS		
SELECT			STROBE $\bar{G}$	Y	W
C	B	A			
X	X	X	H	L	H
L	L	L	L	D0	$\bar{D}0$
L	L	H	L	D1	$\bar{D}1$
L	H	L	L	D2	$\bar{D}2$
L	H	H	L	D3	$\bar{D}3$
H	L	L	L	D4	$\bar{D}4$
H	L	H	L	D5	$\bar{D}5$
H	H	L	L	D6	$\bar{D}6$
H	H	H	L	D7	$\bar{D}7$

## 7 Application and Implementation

---

### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

---

### 7.1 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each  $V_{CC}$  terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- $\mu\text{F}$  capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- $\mu\text{F}$  and 1- $\mu\text{F}$  capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

### 7.2 Layout

#### 7.2.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or  $V_{CC}$ , whichever makes more sense for the logic function or is more convenient.

## 8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 8.1 Documentation Support (Analog)

#### 8.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

**Table 8-1. Related Links**

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
CD74AC151	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>

### 8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](#). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 8.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 8.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.  
All trademarks are the property of their respective owners.

### 8.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 8.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision * (March 2003) to Revision A (July 2024)	Page
• Added <i>Package Information</i> table, <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Device Functional Modes</i> , Application and Implementation section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section .....	1
• Updated RθJA values: D = 73 to 119.9, all values in °C/W.....	5

## 10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD74AC151E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC151E	Samples
CD74AC151M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC151M	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

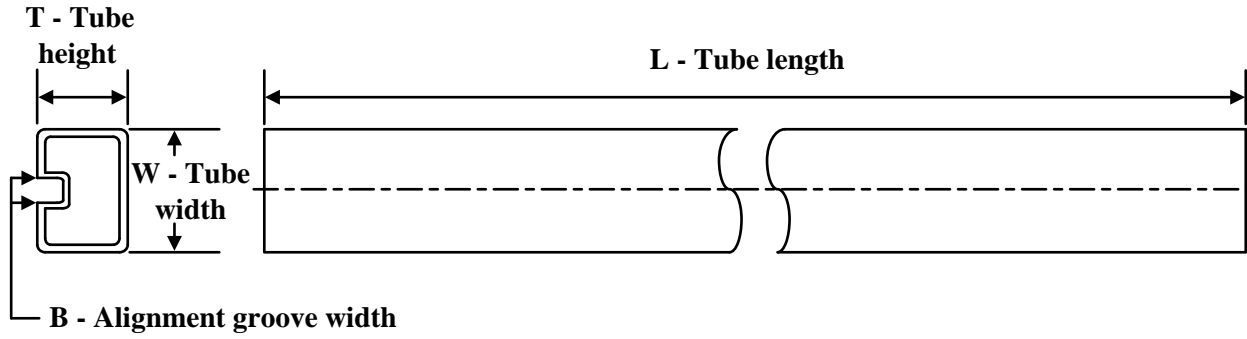
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC151M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC151M96	SOIC	D	16	2500	353.0	353.0	32.0



**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CD74AC151E	N	PDIP	16	25	506	13.97	11230	4.32
CD74AC151E	N	PDIP	16	25	506	13.97	11230	4.32

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2024, Texas Instruments Incorporated